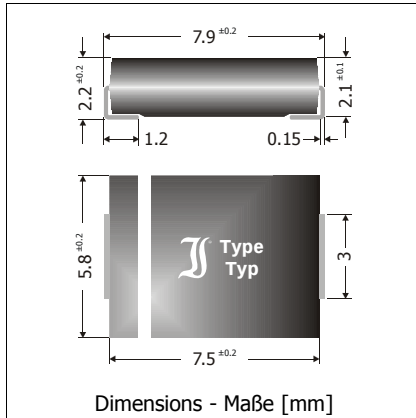


SK82 ... SK810

Surface Mount Schottky Rectifiers Schottky-Gleichrichter für die Oberflächenmontage

Version 2005-11-09



Nominal current – Nennstrom

8 A

 Repetitive peak reverse voltage
 Periodische Spitzensperrspannung

20...100 V

 Plastic case
 Kunststoffgehäuse

 ~ SMC
 ~ DO-214AB

Weight approx. – Gewicht ca.

0.21g

 Plastic material has UL classification 94V-0
 Gehäusematerial UL94V-0 klassifiziert

 Standard packaging taped and reeled
 Standard Lieferform gegurtet auf Rolle


Maximum ratings

Grenzwerte

Type Typ	Repetitive peak reverse voltage Periodische Spitzensperrspannung V_{RRM} [V]	Surge peak reverse voltage Stoßspitzensperrspannung V_{RSM} [V]	Forward voltage Durchlass-Spannung V_F [V] ¹⁾	
			$I_F = 5$ A	$I_F = 8$ A
SK82	20	20	< 0.50	< 0.55
SK83	30	30	< 0.50	< 0.55
SK84	40	40	< 0.50	< 0.55
SK85	50	50	< 0.63	< 0.70
SK86	60	60	< 0.63	< 0.70
SK88	80	80	< 0.77	< 0.85
SK810	100	100	< 0.77	< 0.85

 Max. average forward rectified current, R-load
 Dauergrenzstrom in Einwegschaltung mit R-Last

 $T_T = 100^\circ\text{C}$
 $T_T = 85^\circ\text{C}$
 I_{FAV}
 8 A ²⁾
 8 A ³⁾

 Repetitive peak forward current
 Periodischer Spitzenstrom

 $f > 15$ Hz

 I_{FRM}
 30 A ²⁾
 27 A ³⁾

 Peak forward surge current, 50/60 Hz half sine-wave
 Stoßstrom für eine 50/60 Hz Sinus-Halbwellen

 $T_A = 25^\circ\text{C}$
 I_{FSM}
 140/150 A ²⁾
 125/135 A ³⁾

 Rating for fusing, $t < 10$ ms
 Grenzlastintegral, $t < 10$ ms

 $T_A = 25^\circ\text{C}$
 i^2t
 100 A²s ²⁾
 78 A²s ³⁾

 Operating junction temperature – Sperrschichttemperatur
 Storage temperature – Lagerungstemperatur

 T_j
 T_s

 -50...+150°C
 -50...+150°C

1 $T_j = 25^\circ\text{C}$
 2 SK82 ... SK86
 3 SK88 ... SK810

Characteristics

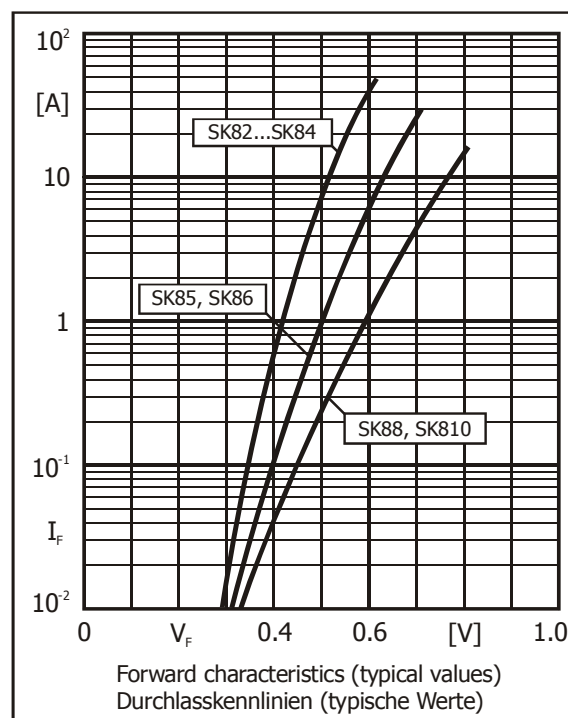
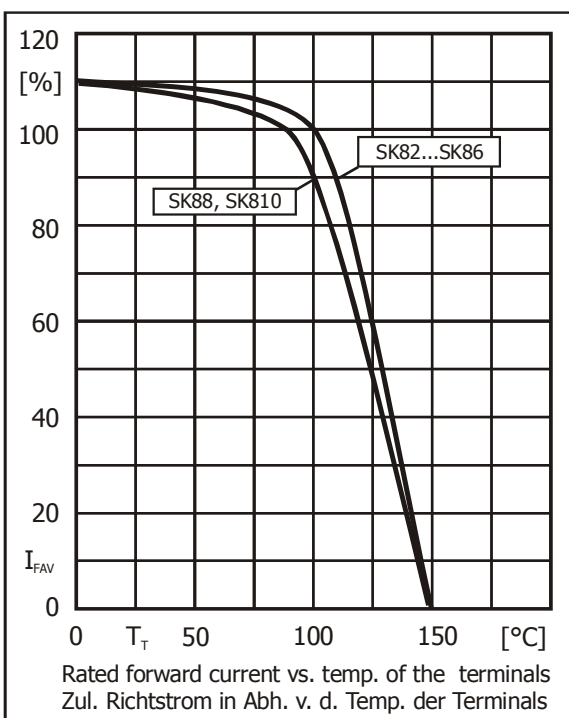
Leakage current
Sperrstrom

 $T_j = 25^\circ\text{C}$
 $V_R = V_{RRM}$
 I_R
 $< 200 \mu\text{A}$
 $T_j = 100^\circ\text{C}$
 $V_R = V_{RRM}$
 I_R
 $< 20 \text{ mA}$

Thermal resistance junction to ambient air
Wärmewiderstand Sperrschicht – umgebende Luft

 R_{thA}
 $< 40 \text{ K/W}^1)$

Thermal resistance junction to terminal
Wärmewiderstand Sperrschicht – Anschluss

 R_{thT}
 $< 10 \text{ K/W}$


1 Mounted on P.C. board with 50 mm² copper pads at each terminal
Montage auf Leiterplatte mit 50 mm² Kupferbelag (Lötpad) an jedem Anschluss